



Material Content Data Sheet



Sales Product Name		ICE3BR1765JZ		Issued		1. August 2018		
MA#		MA000979876						
Package		PG-DIP-7-4		Weight*		652.60 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.344	0.51	0.51	5124	5124
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74	
	non noble metal	zinc	7440-66-6	0.194	0.03		298	
	non noble metal	iron	7439-89-6	3.884	0.60		5952	
wire	non noble metal	copper	7440-50-8	157.726	24.17	24.81	241690	248014
	noble metal	gold	7440-57-5	0.293	0.04	0.04	449	449
	encapsulation	organic material	carbon black	1333-86-4	1.431	0.22		2193
encapsulation	plastics	epoxy resin	-	46.270	7.09		70902	
	inorganic material	silicondioxide	60676-86-0	429.311	65.79	73.10	657850	730945
leadfinish	non noble metal	tin	7440-31-5	6.460	0.99	0.99	9898	9898
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2928	2928
glue	plastics	epoxy resin	-	0.259	0.04		396	
	noble metal	silver	7440-22-4	1.466	0.22	0.26	2246	2642
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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